

1A, 100V - 200V Ultra Fast Surface Mount Rectifier

FEATURES

- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency switching
- DC/DC
- Snubber

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.027g (approximately)

| KEY PARAMETERS | | | |
|--------------------|------------|----|--|
| PARAMETER VALUE UN | | | |
| I _F | 1 | А | |
| V _{RRM} | 100 - 200 | V | |
| I _{FSM} | 45 | А | |
| T _{J MAX} | 175 | °C | |
| Package | SOD-128 | | |
| Configuration | Single die | | |









| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | |
|---|-----------|---------------------|-------------|--------|------|
| PARAMETER | | SYMBOL | PU1BFS | PU1DFS | UNIT |
| Marking code on the device | | | PU1BFS | PU1DFS | |
| Repetitive peak reverse voltage | | V _{RRM} | 100 | 200 | V |
| Reverse voltage, total rms value | | V _{R(RMS)} | 70 | 140 | V |
| Forward current | | I _F | 1 | | А |
| Surge peak forward current single half t = 8.3m | | | 45 | | ^ |
| sine-wave superimposed on rated load | t = 1.0ms | IFSM | 100 | | A |
| Junction temperature | | TJ | -55 to +175 | | °C |
| Storage temperature | | T _{STG} | -55 to +175 | | °C |



Taiwan Semiconductor

| THERMAL PERFORMANCE | | | | | |
|--|------------------|-----|------|--|--|
| PARAMETER | SYMBOL | ТҮР | UNIT | | |
| Junction-to-lead thermal resistance | $R_{\Theta JL}$ | 17 | °C/W | | |
| Junction-to-ambient thermal resistance | R _{eja} | 75 | °C/W | | |
| Junction-to-case thermal resistance | R _{eJC} | 20 | °C/W | | |

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

| ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted) | | | | | |
|--|--|-----------------|------|------|------|
| PARAMETER | CONDITIONS | SYMBOL | ТҮР | MAX | UNIT |
| | $I_F = 0.5A, T_J = 25^{\circ}C$ | | 0.79 | - | V |
| Forward valtage ⁽¹⁾ | $I_F = 1.0A, T_J = 25^{\circ}C$ | N/ | 0.84 | 0.93 | V |
| Forward voltage | $I_F = 0.5A, T_J = 125^{\circ}C$ | VF | 0.64 | - | V |
| | $I_F = 1.0A, T_J = 125^{\circ}C$ | | 0.70 | - | V |
| Bowerses ourrent @ roted \/ ⁽²⁾ | $T_J = 25^{\circ}C$ | 1 | - | 2 | μA |
| Reverse current @ rated v _R | T _J = 125°C | IR | - | 10 | μA |
| Junction capacitance $1 \text{MHz}, \text{ V}_{\text{R}} = 4.0 \text{V}$ | | CJ | 19 | - | pF |
| Boyoraa raaayary tima | $I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$ | + | - | 25 | ns |
| Reverse recovery lime | $I_F = 1.0A$, di/dt = 50A/µs, $V_R = 30V$ | ۲r | 34 | - | |
| Reverse recovery current | | I _{RM} | 3.4 | - | А |
| Reverse recovery charge | $I_F = 1.0A$, di/dt = 200A/µs, $V_R = 100V$ | Q _{rr} | 27 | - | nC |
| Reverse recovery time | | t _{rr} | 19 | - | ns |

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

| ORDERING INFORMATION | | | |
|------------------------------|---------|---------------------|--|
| ORDERING CODE ⁽¹⁾ | PACKAGE | PACKING | |
| PU1xFS | SOD-128 | 14,000/ Tape & Reel | |

Notes:

1. "x" defines voltage from 100V(PU1BFS) to 200V(PU1DFS)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$



Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics



 $(H) = 100 \\ (H) = 100 \\ (H)$

Fig.4 Typical Forward Characteristics



Fig.5 Typical Transient Thermal Impedance



Fig.2 Typical Junction Capacitance



Taiwan Semiconductor





| Unit (m | | (mm) | nm) Unit (ind | |
|---------|------|------|---------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.90 | 1.10 | 0.035 | 0.043 |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 |
| b | 1.60 | 1.90 | 0.063 | 0.075 |
| с | 0.10 | 0.22 | 0.004 | 0.009 |
| D | 2.30 | 2.70 | 0.091 | 0.106 |
| E | 4.40 | 5.00 | 0.173 | 0.197 |
| E1 | 3.60 | 4.00 | 0.142 | 0.157 |
| L | 0.40 | 0.80 | 0.016 | 0.031 |
| L1 | 0.30 | 0.60 | 0.012 | 0.024 |

SUGGESTED PAD LAYOUT



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| А | 2.10 | 0.083 |
| В | 1.40 | 0.055 |
| С | 4.40 | 0.173 |
| D | 3.00 | 0.118 |
| E | 5.80 | 0.228 |

MARKING DIAGRAM



| P/N = Marking | Code |
|---------------|------|
|---------------|------|

YW = Date Code

F = Factory Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.